	Hits	Search Text	DBs
1	8	(("4294650") or ("5259926") or ("5514503") or ("5544582") or ("5678483") or ("5701815") or ("6001515") or ("6356318")).PN.	US-PGPUB; USPAT
2	407	((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
3	323	((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3) and contact$4 and ((substrate or transfer) same (metal$4 or semiconductor or "SiO.sub.2" or SiO$2 or insulat$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
4	222	((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3) and contact$4 and ((substrate or transfer) same (metal$4 or semiconductor or "SiO.sub.2" or SiO$2 or insulat$4)) and (photoresist or resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
5	146	((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3) and contact$4 and ((substrate or transfer) same (metal$4 or semiconductor or "SiO.sub.2" or SiO$2 or insulat$4) same (photoresist or resist))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
6	48	((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3) and ((substrate or transfer) same (metal$4 or semiconductor or "SiO.sub.2" or SiO$2 or insulat$4) same (photoresist or resist)) and ((substrate or clich$3) same (etch$4 near5 (object or process$4)) same (fill$4 or deposit$4 or form$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
7	6	430/322.ccls. and ((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
8	4	101/153.ccls. and ((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
9	3	430/324.ccls. and ((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
10	6	101/34.ccls. and ((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	38	"101"/$.ccls. and ((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
12	50	"430"/$.ccls. and ((substrate or wafer) same (panel$3 or unit or clich$2 or area or region or divid$3) same (groove or etch$2 or recess$3 or raise$2) same pattern$4) and (transfer$3 or roll$3 or collector) and (print$3 near5 roll$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB